
**Standardizacija mehanskih lastnosti polprevodniških elementov – 6-2. del:
Splošna pravila za pripravo tehničnih risb okrovov polprevodniških elementov
za površinsko montažo - Vodilo za konstruiranje okrovov s krogličnimi in
stebričnimi priključki v rastru 1,50 mm, 1,27 mm in 1,00 mm (IEC 60191-2-
6:2001)**

Mechanical standardization of semiconductor devices - Part 6-2: General rules for
the preparation of outline drawings of surface mounted semiconductor device
packages - Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and
column terminal packages (IEC 60191-2-6:2001)

[SIST EN 60191-6-2:2005](https://standards.iteh.ai/catalog/standards/sist/7b748768-58c7-4f93-b3cb-b9e550c8883b/sist-en-60191-6-2-2005)

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English version

Mechanical standardization of semiconductor devices
Part 6-2: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages -
Design guide for 1,50 mm, 1,27 mm and 1,00 mm
pitch ball and column terminal packages
 (IEC 60191-6-2:2001)

Normalisation mécanique des
dispositifs à semiconducteurs

Part 6-2: Règles générales pour la
préparation des dessins d'encombrement
des dispositifs à semiconducteurs pour
montage en surface -

Guide de conception pour les boîtiers
à broches en forme de billes

et de colonnes, avec des pas de
1,50 mm, 1,27 mm et 1,00 mm

(CEI 60191-6-2:2001)

Mechanische Normung von
Halbleiterbauelementen

Teil 6-2: Allgemeine Regeln für
die Erstellung von Gehäusezeichnungen

von SMD-Halbleitergehäusen -
Konstruktionsleitfaden für Gehäuse

mit Kugel- und Säulenanschlüssen
in einem Raster von

1,50 mm, 1,27 mm und 1,00 mm

(IEC 60191-6-2:2001)

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Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/460/FDIS, future edition 1 of IEC 60191-6-2, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-2 on 2002-02-01.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2002-11-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2005-02-01

Annexes designated "normative" are part of the body of the standard.

In this standard, annex ZA is normative.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-2:2001 was approved by CENELEC as a European Standard without any modification.

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Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates, by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references, the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191	Series	Mechanical standardization of semiconductor devices	EN 60191	Series

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INTERNATIONAL STANDARD

IEC 60191-6-2

First edition
2001-12

Mechanical standardization of semiconductor devices –

Part 6-2:

General rules for the preparation of outline drawings of surface mounted semiconductor device packages –

Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages

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Normalisation mécanique des dispositifs à semiconducteurs –

Partie 6-2:

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

**Part 6-2: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
Design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball
and column terminal packages**

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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International Standard IEC 60191-6-2 has been prepared by subcommittee SC 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/460//FDIS	47D/471/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2004. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

The contents of the corrigendum of October 2002 have been included in this copy.

INTRODUCTION

This design guide is intended to standardize the requirements for all ball and column terminal packages in order to establish common rules for terminal shapes, irrespective of device and package types.

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